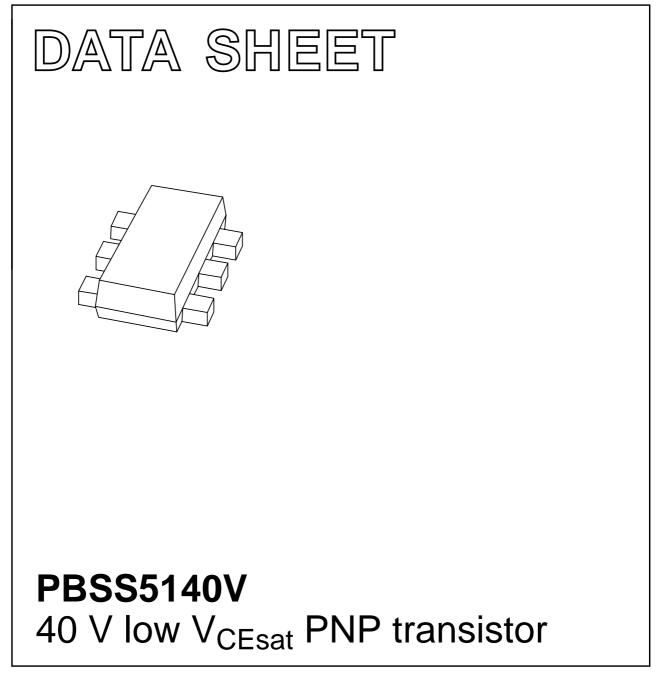
DISCRETE SEMICONDUCTORS



Product specification Supersedes data of 2001 Oct 19 2002 Mar 20



FEATURES

- 300 mW total power dissipation
- Very small 1.6 mm \times 1.2 mm \times 0.55 mm ultra thin package
- · Improved thermal behaviour due to flat leads
- Self alignment during soldering due to straight leads
- Low collector-emitter saturation voltage
- High current capability

APPLICATIONS

- General purpose switching and muting
- LCD back lighting
- Supply line switching circuits
- Battery driven equipment (mobile phones, video cameras and hand-held devices).

DESCRIPTION

PNP low $V_{CE sat}$ transistor in a SOT666 plastic package. NPN complement: PBSS4140V.

MARKING

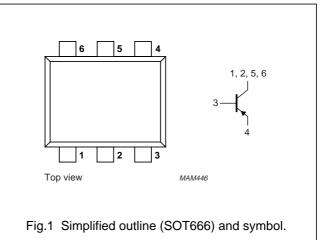
TYPE NUMBER	MARKING CODE		
PBSS5140V	25		

QUICK REFERENCE DATA

SYMBOL	PARAMETER	MAX.	UNIT	
V _{CEO}	collector-emitter voltage	-40	V	
I _C	collector current (DC)	-1	A	
I _{CM}	peak collector current	-2	A	
R _{CEsat}	equivalent on-resistance	<340	mΩ	

PINNING

PIN	DESCRIPTION
1	collector
2	collector
3	base
4	emitter
5	collector
6	collector



PBSS5140V

40 V low V_{CEsat} PNP transistor

PBSS5140V

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _{CBO}	collector-base voltage	open emitter	_	-40	V
V _{CEO}	collector-emitter voltage	open base	-	-40	V
V _{EBO}	emitter-base voltage	open collector	_	-5	V
I _C	collector current (DC)		_	-1	A
I _{CM}	peak collector current		_	-2	A
I _B	base current (DC)		_	-300	mA
I _{BM}	peak base current		_	-1	A
P _{tot}	total power dissipation	T _{amb} ≤ 25 °C; note 1	_	300	mW
		$T_{amb} \le 25 \ ^{\circ}C; note 2$	_	500	mW
T _{stg}	storage temperature		-65	+150	°C
Tj	junction temperature		-	150	°C
T _{amb}	operating ambient temperature		-65	+150	°C

Notes

- 1. Device mounted on a printed-circuit board, single side copper, tinplated and standard footprint.
- 2. Device mounted on a printed-circuit board, single side copper, tinplated and mounting pad for collector 1 cm².

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R _{th j-a}	thermal resistance from junction to ambient	note 1	410	K/W
		note 2	215	K/W

Notes

- 1. Device mounted on a printed-circuit board, single side copper, tinplated and standard footprint.
- 2. Device mounted on a printed-circuit board, single side copper, tinplated and mounting pad for collector 1 cm².

Soldering

The only recommended soldering is reflow soldering.

40 V low V_{CEsat} PNP transistor

PBSS5140V

CHARACTERISTICS

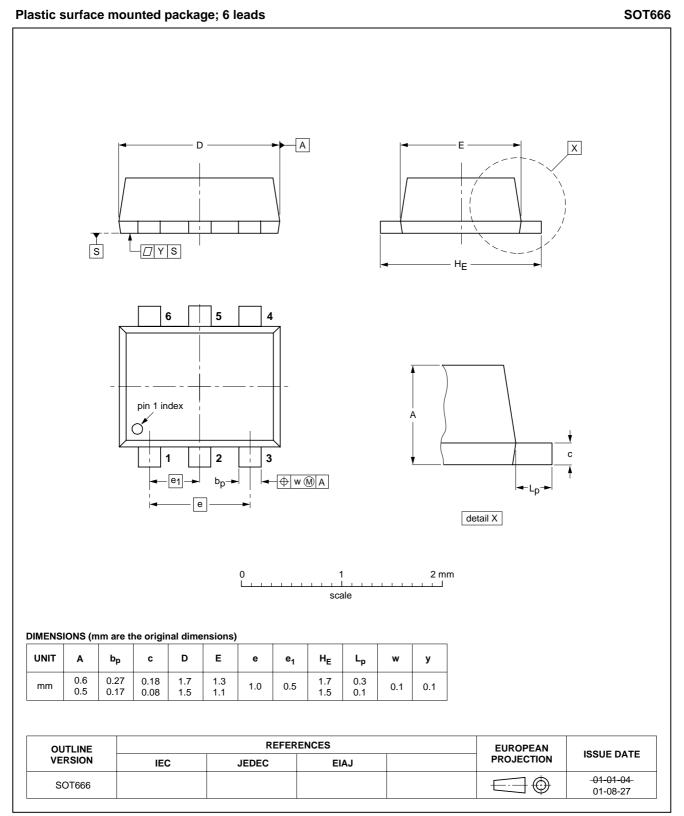
 T_{amb} = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I _{CBO}	collector-base cut-off current	$V_{CB} = -40 \text{ V}; I_E = 0$	_	-	-100	nA
		$V_{CB} = -40 \text{ V}; \text{ I}_{E} = 0; \text{ T}_{amb} = 150 ^{\circ}\text{C}$	_	-	-50	μA
I _{CEO}	collector-emitter cut-off current	$V_{CE} = -30 \text{ V}; I_B = 0$	_	-	-100	nA
I _{EBO}	emitter-base cut-off current	$V_{EB} = -5 \text{ V}; I_{C} = 0$	-	-	-100	nA
h _{FE}	DC current gain	$V_{CE} = -5 \text{ V}; I_C = -1 \text{ mA}$	300	-	-	
		$V_{CE} = -5 \text{ V}; I_{C} = -100 \text{ mA}$	300	-	800	
		$V_{CE} = -5 \text{ V}; I_C = -500 \text{ mA}$	250	-	-	
		$V_{CE} = -5 \text{ V}; I_C = -1 \text{ A}$	160	-	-	
V _{CEsat}	collector-emitter saturation voltage	$I_{\rm C} = -100 \text{ mA}; I_{\rm B} = -1 \text{ mA}$	_	-80	-140	mV
		$I_{\rm C} = -500 \text{ mA}; I_{\rm B} = -50 \text{ mA}$	_	-120	-170	mV
		$I_{\rm C} = -1$ A; $I_{\rm B} = -100$ mA	_	-200	-310	mV
R _{CEsat}	equivalent on-resistance	$I_{C} = -500 \text{ mA}; I_{B} = -50 \text{ mA}; \text{ note } 1$	_	240	<340	mΩ
V _{BEsat}	base-emitter saturation voltage	$I_{\rm C} = -1$ A; $I_{\rm B} = -50$ mA	_	-	-1.1	V
V _{BEon}	base-emitter turn-on voltage	$V_{CE} = -5 \text{ V}; \text{ I}_{C} = -1 \text{ A}$	_	-	-1	V
f _T	transition frequency	$I_{C} = -50 \text{ mA}; V_{CE} = -10 \text{ V};$ f = 100 MHz	150	-	-	MHz
C _c	collector capacitance	$V_{CB} = -10 \text{ V}; \text{ I}_{E} = \text{ I}_{e} = 0; \text{ f} = 1 \text{ MHz}$	_	-	12	pF

Note

1. Pulse test: $t_p \leq 300 \ \mu s; \ \delta \leq 0.02.$

PACKAGE OUTLINE



PBSS5140V

PBSS5140V

DATA SHEET STATUS

DATA SHEET STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITIONS
Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product.
Product data	Production	This data sheet contains data from the product specification. Philips Semiconductors reserves the right to make changes at any time in order to improve the design, manufacturing and supply. Changes will be communicated according to the Customer Product/Process Change Notification (CPCN) procedure SNW-SQ-650A.

Notes

- 1. Please consult the most recently issued data sheet before initiating or completing a design.
- 2. The product status of the device(s) described in this data sheet may have changed since this data sheet was published. The latest information is available on the Internet at URL http://www.semiconductors.philips.com.

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Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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PBSS5140V

NOTES

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